

# LL01V54AT2510

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# LL01V54AT2510

## 4-Channel Ultra Low Capacitance Uni-Directional TVS For ESD Protection 1.5V

### Features

- Low capacitance: 0.38pF (typ.).
- Low leakage current:  $0.01\mu\text{A}@V_{\text{RWM}}$  (Max.).
- Low clamping voltage.
- Protects four I/O lines.
- Transient protection for high-speed data lines  
IEC61000-4-2 (ESD)  $\pm 10\text{kV}$  (Air),  $\pm 10\text{kV}$  (Contact).  
IEC 61000-4-5 (Lightning) 3.0A (8/20 $\mu\text{s}$ ).
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates halogen-free parts, ex. LL01V54AT2510-H

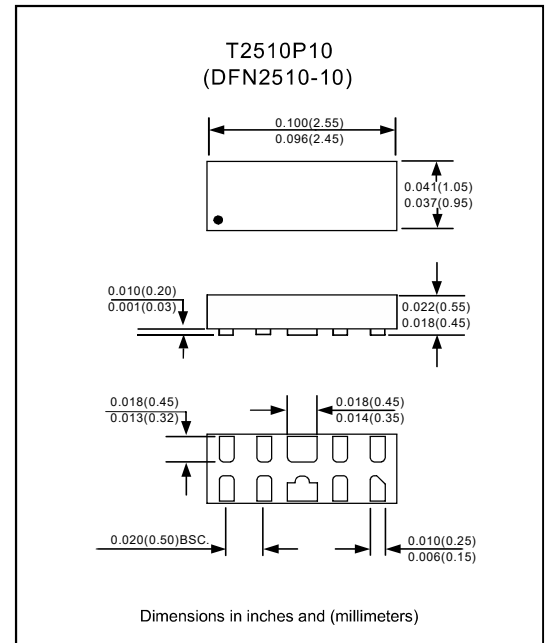
### Applications

- Portable applications, communication systems.
- Computers and peripherals.
- USB 2.0/3.0 (Gen 1), HDMI 1.3/1.4, eSATA and display port.

### Mechanical data

- Epoxy: UL94-V0 rated flame retardant.
- Case : Molded plastic, T2510P10 (DFN2510-10).
- Mounting Position : Any.

### Package outline



### Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter                                | Symbol           | Value       | Units            |
|------------------------------------------|------------------|-------------|------------------|
| Peak pulse current (8/20 $\mu\text{s}$ ) | $I_{\text{PP}}$  | 3           | A                |
| ESD per IEC61000-4-2 (Air)               | $V_{\text{ESD}}$ | $\pm 10$    | KV               |
| ESD per IEC61000-4-2 (Contact)           |                  | $\pm 10$    |                  |
| Operating temperature                    | $T_J$            | +125        | $^\circ\text{C}$ |
| Storage temperature range                | $T_{\text{STG}}$ | -55 to +150 | $^\circ\text{C}$ |

### Electrical Characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

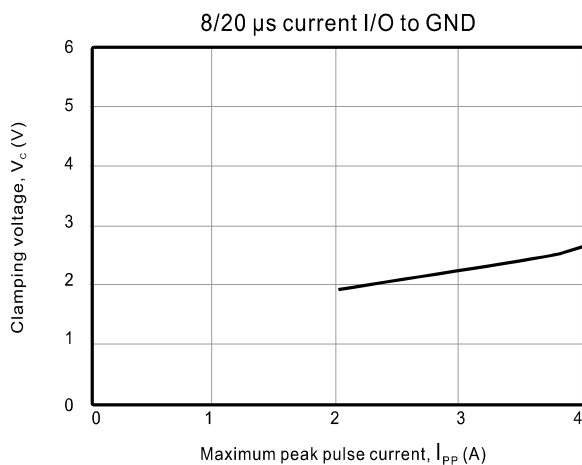
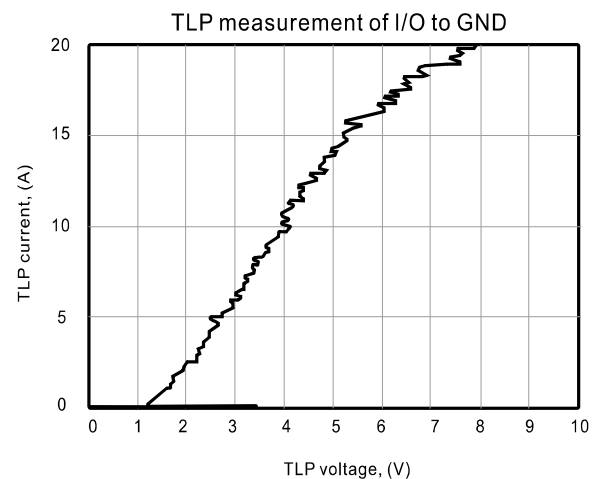
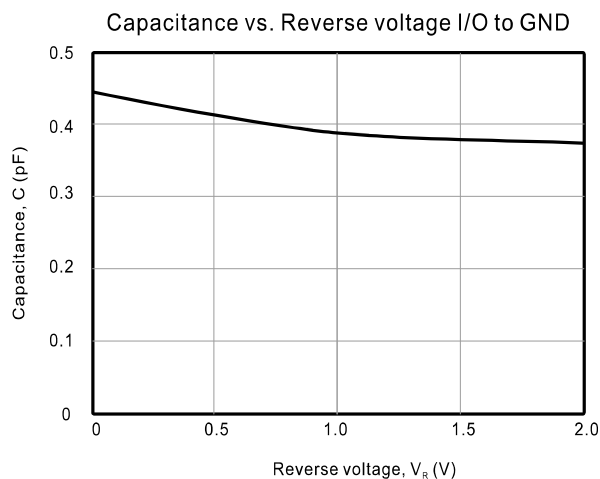
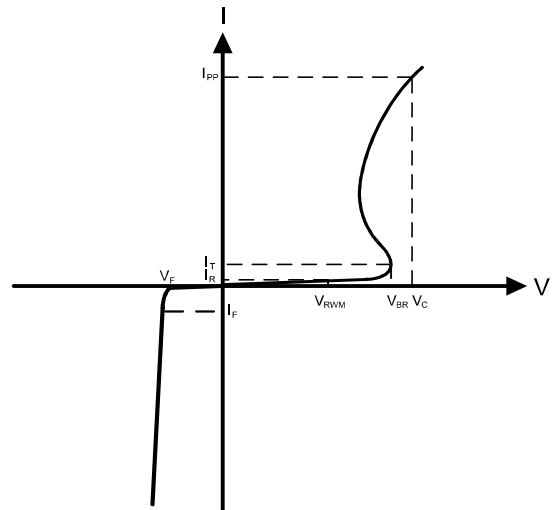
| Parameter                  | Conditions                                                                  | Symbol           | Min. | Typ. | Max. | Unit     |
|----------------------------|-----------------------------------------------------------------------------|------------------|------|------|------|----------|
| Reverse working voltage    |                                                                             | $V_{\text{RWM}}$ |      |      | 1.5  | V        |
| Reverse leakage current    | $V_{\text{RWM}}=1.5\text{V}$ , $T_A=25^\circ\text{C}$ (Between I/O and GND) | $I_{\text{R}}$   |      | 1    | 10   | nA       |
| Reverse breakdown voltage  | $I_{\text{T}}=1\text{mA}$ (Between I/O and GND)                             | $V_{\text{BR}}$  | 2.5  | 3.3  |      | V        |
| Clamping voltage           | $I_{\text{PP}}=3\text{A}$ , $t_p=8/20\mu\text{s}$ (Between I/O and GND)     | $V_{\text{C}}$   |      | 2.3  |      | V        |
| Clamping voltage           | $I_{\text{PP}}=8.0\text{A}$ , $t_p=100\text{ns}$ (Note1)                    | $V_{\text{C}}$   |      | 3.45 |      | V        |
|                            | $I_{\text{PP}}=16.0\text{A}$ , $t_p=100\text{ns}$ (Note1)                   |                  |      | 5.70 |      |          |
| Inverse dynamic resistance | $I_{\text{PP}}=12.0\text{A}$ , $t_p=100\text{ns}$ (Note1)                   | $R_{\text{dyn}}$ |      | 0.28 |      | $\Omega$ |
| Parasitic Capacitance      | $V_{\text{R}}=1\text{V}$ , $f=1.0\text{MHz}$ (Between I/O and GND)          | $C_{\text{ESD}}$ |      | 0.38 | 0.45 | pF       |

Notes : 1. Measurements performed using a 100ns transmission line pulse(TLP) system, between I/O and GND.

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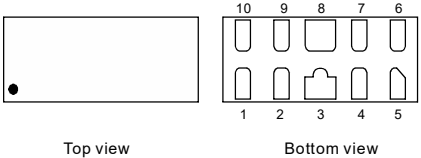
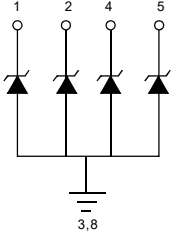
## Rating and characteristic curves

| Symbol    | Parameter                          |
|-----------|------------------------------------|
| $V_{RWM}$ | Nominal reverse working voltage    |
| $I_R$     | Reverse leakage current@ $V_{RWM}$ |
| $V_{BR}$  | Reverse breakdown voltage@ $I_T$   |
| $I_T$     | Test current for reverse breakdown |
| $V_C$     | Clamping voltage@ $I_{PP}$         |
| $I_{PP}$  | Maximum peak pulse current         |
| $C_{ESD}$ | Parasitic capacitance              |
| $I_F$     | Forward current                    |
| $V_F$     | Forward voltage @ $I_F$            |



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Pinning information

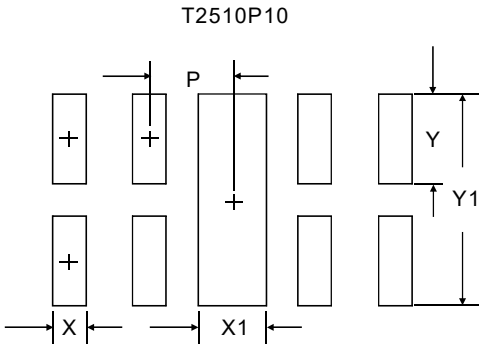
| Pin                                               | Simplified outline                                                                                                   | Circuit diagram                                                                     |
|---------------------------------------------------|----------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------|
| Pin 1,2,4,5 I/O<br>Pin 3,8 GND<br>Pin 6,7,9,10 NC |  <p>Top view</p> <p>Bottom view</p> |  |

Marking

| Type number   | Marking code |
|---------------|--------------|
| LL01V54AT2510 | 11XXXX       |

\* "11" is part number, fixed.  
"XXXX" is ther wafer lot code.

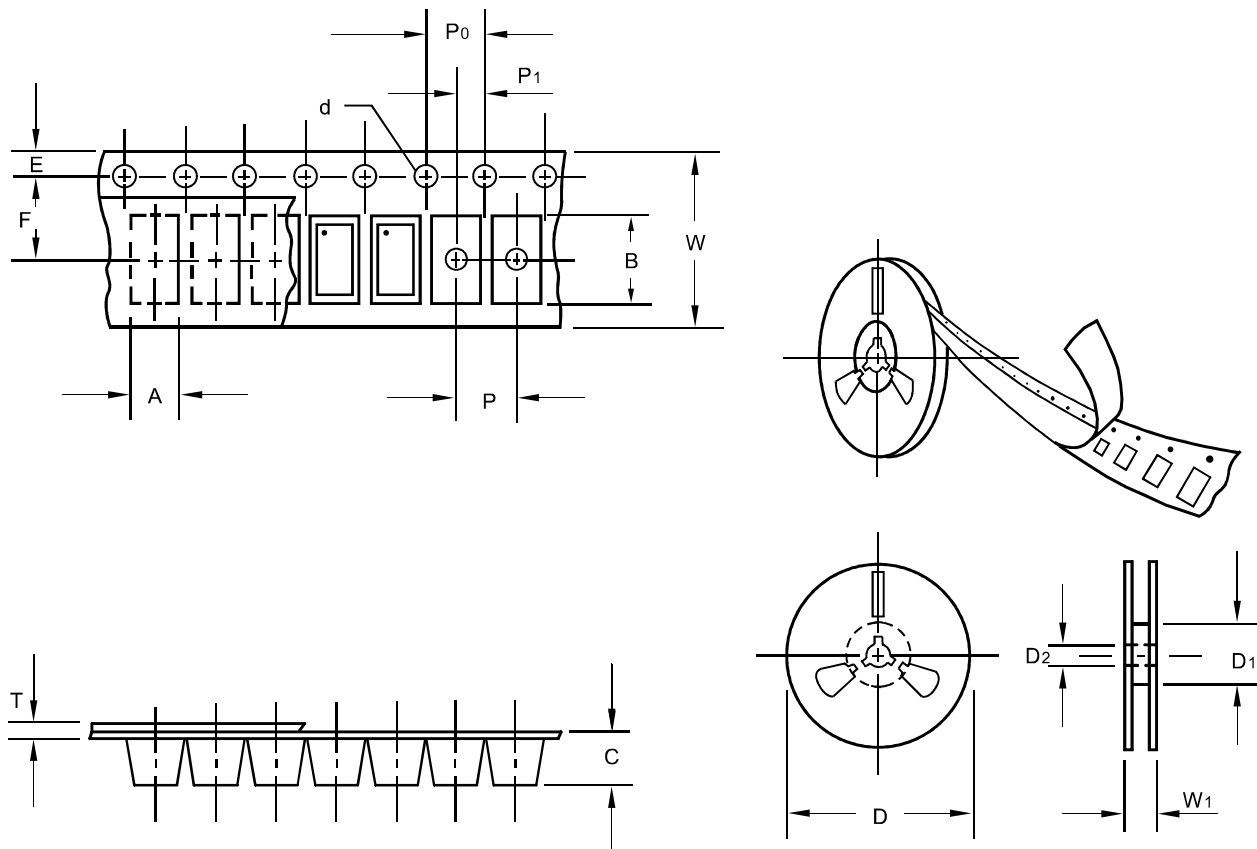
Suggested solder pad layout



| DIMENSIONS |        |             |
|------------|--------|-------------|
| DIM        | INCHES | MILLIMETERS |
| P          | 0.020  | 0.50        |
| X          | 0.012  | 0.30        |
| X1         | 0.016  | 0.40        |
| Y          | 0.019  | 0.48        |
| Y1         | 0.047  | 1.20        |

## LL01V54AT2510

## Packing information



unit:mm

| Item                      | Symbol | Tolerance | T2510P10 |
|---------------------------|--------|-----------|----------|
| Carrier width             | A      | 0.1       | 1.23     |
| Carrier length            | B      | 0.1       | 2.70     |
| Carrier depth             | C      | 0.1       | 0.70     |
| Sprocket hole             | d      | 0.1       | 1.50     |
| 13" Reel outside diameter | D      | 2.0       | -        |
| 13" Reel inner diameter   | D1     | min       | -        |
| 7" Reel outside diameter  | D2     | 2.0       | 178.00   |
| 7" Reel inner diameter    | D1     | min       | 60.00    |
| Feed hole diameter        | D2     | 0.2       | 13.00    |
| Sprocket hole position    | E      | 0.1       | 1.75     |
| Punch hole position       | F      | 0.1       | 3.50     |
| Punch hole pitch          | P      | 0.1       | 4.00     |
| Sprocket hole pitch       | P0     | 0.1       | 4.00     |
| Embossment center         | P1     | 0.1       | 2.00     |
| Overall tape thickness    | T      | 0.1       | 0.25     |
| Tape width                | W      | 0.3       | 8.00     |

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

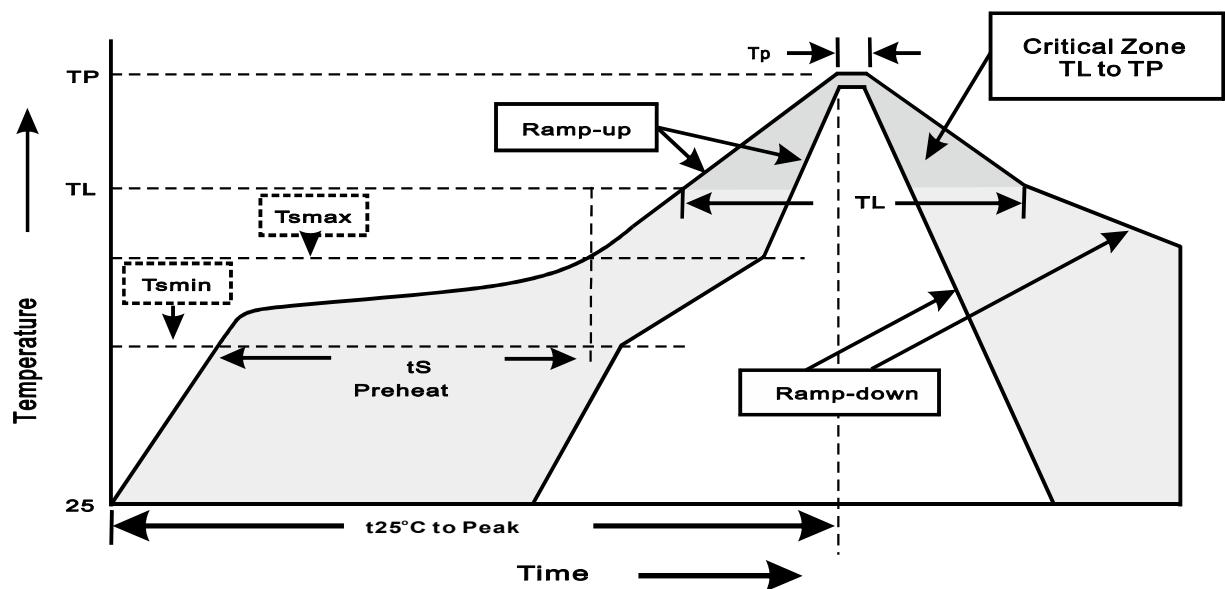
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## Reel packing

| PACKAGE  | REEL SIZE | REEL (pcs) | COMPONENT SPACING (m/m) | BOX (pcs) | INNER BOX (m/m) | REEL DIA, (m/m) | CARTON SIZE (m/m) | CARTON (pcs) |
|----------|-----------|------------|-------------------------|-----------|-----------------|-----------------|-------------------|--------------|
| T2510P10 | 7"        | 3,000      | 4.0                     | 30,000    | 183*123*183     | 178             | 382*257*387       | 240,000      |

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



### 3.Reflow soldering

| Profile Feature                                                                                                             | Soldering Condition         |
|-----------------------------------------------------------------------------------------------------------------------------|-----------------------------|
| Average ramp-up rate(T <sub>L</sub> to T <sub>P</sub> )                                                                     | <3°C/sec                    |
| Preheat<br>-Temperature Min(T <sub>min</sub> )<br>-Temperature Max(T <sub>max</sub> )<br>-Time(min to max)(t <sub>s</sub> ) | 150°C<br>200°C<br>60~120sec |
| T <sub>max</sub> to T <sub>L</sub><br>-Ramp-upRate                                                                          | <3°C/sec                    |
| Time maintained above:<br>-Temperature(T <sub>L</sub> )<br>-Time(t <sub>L</sub> )                                           | 217°C<br>60~260sec          |
| Peak Temperature(T <sub>P</sub> )                                                                                           | 255°C-0/+5°C                |
| Time within 5°C of actual Peak Temperature(t <sub>P</sub> )                                                                 | 10~30sec                    |
| Ramp-down Rate                                                                                                              | <6°C/sec                    |
| Time 25°C to Peak Temperature                                                                                               | <6minutes                   |